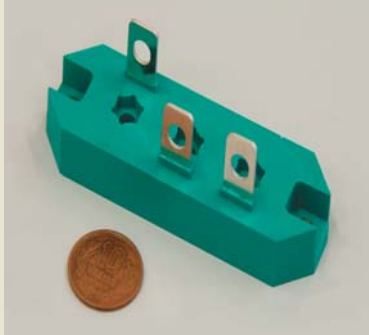


A SiC module developed by Fuji Electric Holdings Co., Ltd. The development of new packaging technologies also accelerates based on new materials (page 22).



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